

EDCON-COMPONENTS



Designed for surface mounting on high density circuit board

Emboss carrier tape packing systems is available for automatic insertion



Technical Informations

Voltage:	16Volt
Range:	22µF
Dimension; D x L mm	5x5,4mm
Impedance (Ω) max., at 20°C, 100kHz	15,7Ω
Ripple Current (mA rms) at 105°C, 100kHz	39mA

Ordering Code			
160	Voltage		
220	Range		
D=	B	L=	0

- Low Leakage current (0,5µA to 3,3µA max).
- Low cost for replacement of some tantalum applications
- Low Impedance with Operating Temperatur Range of -40°C ~ +85°C
- Load Life of 2000hours

Leakage current max.	I = 0,002CV or 0,5µA whichever is greater (after 2 minutes)	
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Capacitance tolerance	± 20% at 120Hz, 20°C																
Dissipation factor max. (at 120Hz, 20°C)		WV															
	Tanδ	Ø4 ~ Ø6,3mm	6,3	10	16	25	35	50									
			0,24	0,20	0,16	0,14	0,12	0,10									

Low Temperatur characteristics (Impedance ratio at 120Hz)		WV															
		Z-25°C / Z+20°C	6,3	10	16	25	35	50									
		Z-40°C / Z+20°C	4	3	2	2	2	2									
			8	6	4	4	3	3									

Load Life (after application of the rated voltage for 2000hrs at 85°C	Leakage current	Less than specified value
	Capacitance Change	Within ±25% of initial value
	Tanδ	Less than 200% of specified value
	Ø4 ~ Ø6,3x5,4: 1000hours	

CHIP Low Leakage Current	
Part No.:	I15004

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014	Customer:
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Resistance to soldering heat	After reflow soldering and resistance at room temperature, they meet the characteristics requirements listed at underside	
	Leakage current	Less than specified value
	Capacitance Change	Within $\pm 10\%$ of initial value
	Tan δ	Less than specified value

FREQUENCY COEFFICIENT OF PERMISSIBLE RIPPLE CURRENT					
Frequency	50Hz	120Hz	300Hz	1KHz	10KHz \leq
Coefficient	0,70	1,00	1,17	1,36	1,50

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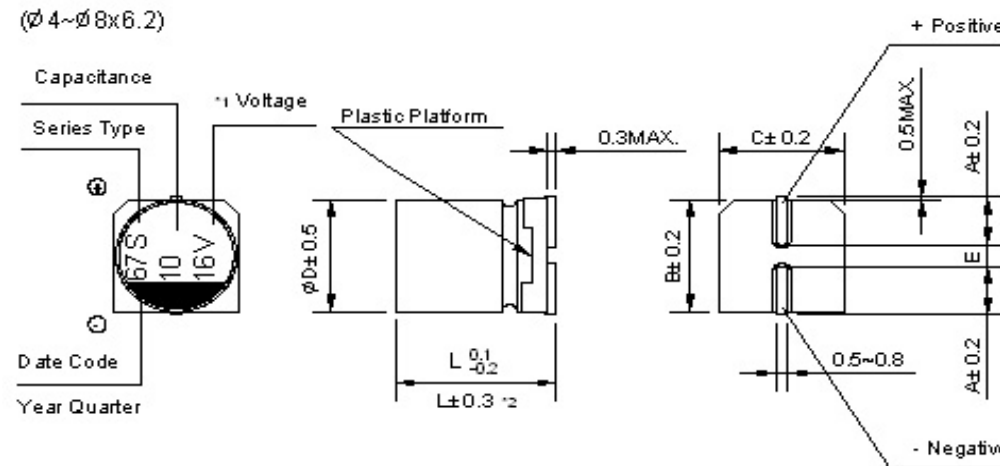


Technical Drawing

Dimension of Size Ø 8x10,5 ~ 16mm



Dimension of Size Ø 4~ 8x6,2mm



D x L	Ø 4 x 5,4	Ø 5 x 5,4	Ø 6,3 x 5,4	Ø 6,3 x 7,7						
A	2,0	2,2	2,6	2,6						
B	4,3	5,3	6,6	6,6						
C	4,3	5,3	6,6	6,6						
E +/-0.2	1,0	1,3	1,9	1,9						
L	5,4	5,4	5,4	7,7						

*1 Voltage mark (6V) represents 6,3V for Ø 4 ~ 10mm

*3 (L +/- 0.5) is applicable to Ø 8x10,5 ~ Ø 10mm

*2 (L +/- 0.3) is applicable to Ø 6,3 ~ 7.7 and Ø 8 + 6,2mm

*4 (L +/- 1.0) is applicable to Ø 12,5 ~ Ø 16mm

RE. Date code and seriew type -1st digit for Year 2nd digit for Quarter, 4 quarter codes in one year area 1,4,7,0

3rd character for Serie S

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www.edcon-components.com

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Ordering Informations

Serie	Voltage Code	Tolerance Code	Range Code	Size Code D	Size Code L	Special function	ROHS	Packing Code		
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I15004	160	M	220	B	0	XX	R	TR		
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look table Voltage Code	M= ±20%	Ordering Code Range	Look table Code D	Look table Code L	XX= No function	R= ROHS Conform N= NON ROHS Conform	TR= Tape Reel Packing BU= Bulk-Ware		
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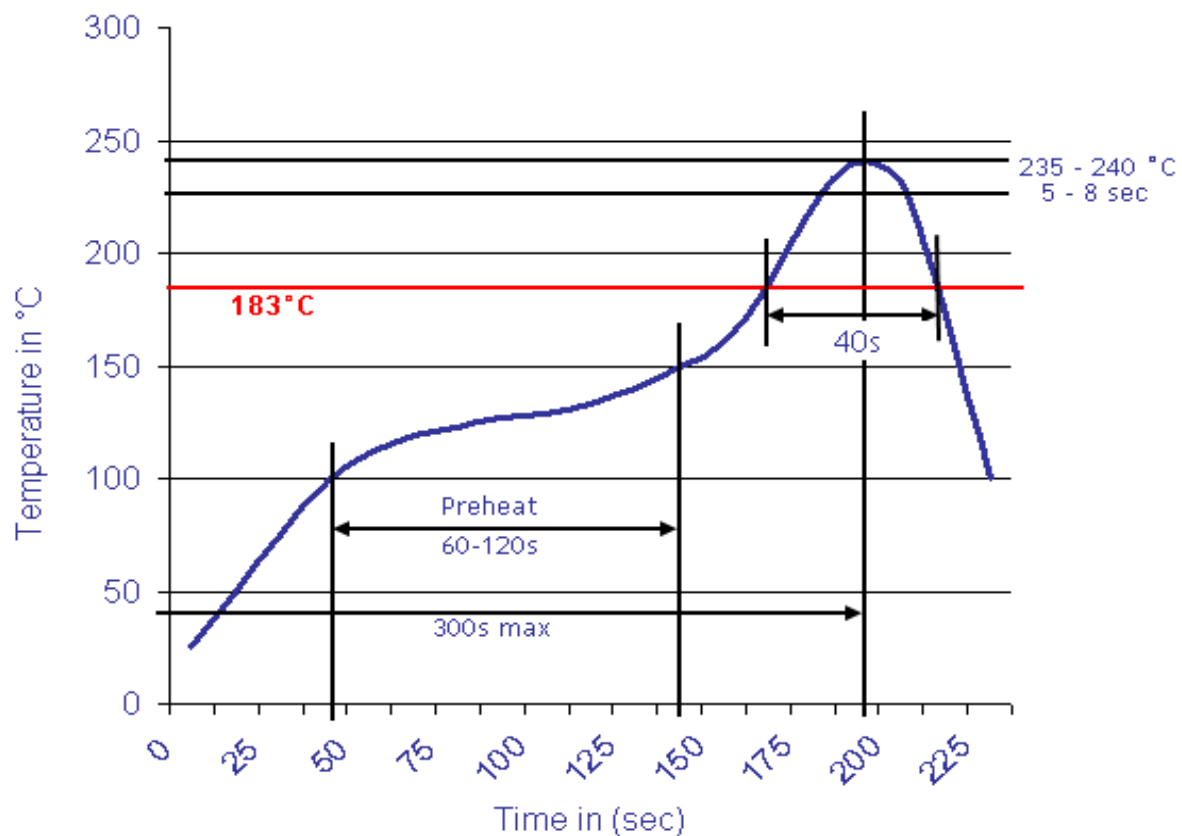


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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



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